

**FORM PTO-1449**  
**LIST OF PATENTS AND PUBLICATIONS**  
**FOR APPLICANT'S INFORMATION**  
**DISCLOSURE STATEMENT**

**ATTY. DOCKET** 10936-38  
**APPLICANT** Junji Kodemura et al  
**FILING DATE** January 4, 2000  
**FOR** Adhesive for Semiconductor Part

**SERIAL NO. 09/462,214**

**UNITED STATES LETTERS PATENT**

~~FOREIGN PATENT DOCUMENTS~~

OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

*[Signature]* a1 Japanese Publication, Society of Industrial Research: Society for Hybrid Microelectronics, Vol. 4, Chapter 6, pages 212-213 (1995)  
*[Signature]* 1/10/01

**EXAMINER**

**DATE CONSIDERED**

1/10/01

**EXAMINER**                    **DATE CONSIDERED**  
**EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.                    549233.01

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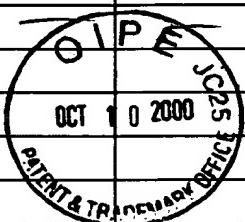
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GROUP 1734

UNITED STATES LETTERS PATENT

## FOREIGN PATENT DOCUMENTS



OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

*[Signature]* ae Derwent Abstract AN 1991-278329 of JP 3-185013 (1991)  
*[Signature]* 1/10/91

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